

Electronic Acknowledgement Receipt

EFS ID:	1444397
Application Number:	10594322
International Application Number:	
Confirmation Number:	3313
Title of Invention:	Epoxy resin composition for the encapsulation of semiconductors and semiconductor devices
First Named Inventor/Applicant Name:	Daisuke Hirokane
Customer Number:	22850
Filer:	Marvin Jay Spivak/Chai Xiong
Filer Authorized By:	Marvin Jay Spivak
Attorney Docket Number:	295408US40PCT
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Oath or Declaration filed	295408usDeclaration.pdf	578602	no	3

Warnings:

Information:**Total Files Size (in bytes):**

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.